



# RoodMicrotec Newsletter

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## RoodMicrotec signs new Sales Channel Agreement with Swiss Altec AG

In August, we signed a sales channel agreement with Altec Electronic AG, which will strengthen our SCM capabilities and offer better and more efficient service to our Swiss customers. We have already had a long and successful business relationship with Altec, a renowned electronics distribution company with over 10 years of trusted experience.

Altec is a service enterprise which sets the end customer as its central focus.

Services and products are constantly being adapted to the changed market conditions. Altec is a very reliable partner in providing the highest quality of service and logistics to our customers.

They will now offer the entire RoodMicrotec services as part of their own portfolio:

- eXtended Supply Chain Services
- Engineering Services
- Test / Programming
- Qualification & Reliability
- End-of-line service
- Failure analysis
- ESD consultations and measurements.

All services will be offered either through Altec or directly by RoodMicrotec.

In order to enhance and accelerate service and logistics, our Swiss customers will have access to the customer services from Altec who will be able to supply them locally, as well as direct technical support from RoodMicrotec.

Our agreement with Altec is therefore a further step in the direction of 'one stop shop' turnkey solutions from a single source for our customers.

Martin Sallenhag, CEO  
Reinhard Pusch, COO

## RoodMicrotec showcasing newest services at electronica Munich 2016



From November 8th to 11th, RoodMicrotec will be featuring its newest services at the bi-annual electronica fair in Munich. Our experts will be available to speak with you directly at our booth (number 101, hall 5). Here is what is new in 2016:

1. ASIC turnkey service
  - We strengthened our position in sensors, mixed signal and RF ASICs
  - We established additional partners for wafer manufacturing, assembly and SiP package design
2. Test and Test Engineering
  - Additional test platform Advantest V93k SoC
  - New Accretech 12" waferprober with cold test option
3. Failure analysis
  - Computer tomograph
  - New analysis method for failure prevention of ceramic capacitors
  - Screening and LAT (Lot Acceptance Test) process on image sensors for space application

We are pleased to introduce our new sales channel partner for Switzerland, Altec Electronic AG, whose COO Mr. Gilbert Lang will be available at our booth to explain the new engagement between RoodMicrotec and Altec and answer any questions you may have.

For a meeting with Mr Lang, or with an expert from RoodMicrotec, please contact [dorothee.rau@roodmicrotec.com](mailto:dorothee.rau@roodmicrotec.com)  
Visit us in hall 5 booth 101 – For further venue details please see: <http://electronica.de/trade-fair/for-visitors/>

# Engin Eser and Alexander Jung join RoodMicrotec as sales managers

We have the pleasure of introducing two newly appointed sales managers.



Engin Eser (43) was appointed as Sales & Marketing Manager for RoodMicrotec in July.

Having worked for various design houses as a layout and development engineer, Engin Eser has experience developing microchips for customers, focussing amongst others on SCM and xSCM. His expertise and his network will be of great value to RoodMicrotec.

Mr Eser said: "I'm very excited to join RoodMicrotec in a time that the industry is showing so much potential."

Mr Eser will cover Germany, France, Sandinavia, Eastern Europe and the Far East.



Alexander Jung (52) joined us in September. He has 22 years of sales experience in the engineering sector in Germany, Austria and Switzerland, and his affinity with the industry makes him ideally suited to manage our key accounts and ASIC Turnkey Services.

Mr Jung said: "I look forward to take on the RoodMicrotec client accounts and apply my experience to a region I know very well."

Mr Jung will cover Germany, Austria, Italy and Switzerland.

## Save the date: RoodMicrotec Seminar in Switzerland – November 22<sup>nd</sup>

At our seminar at Campus Brugg-Windisch we will focus on methods for the reliability assurance of electronic components. RoodMicrotec will unveil the value of "Robustness Validation" in comparison to standards like AEC-Q100.

Today, we go beyond the standard qualification process by assessing the exact conditions where failures could occur such as static aspects, the load in the system or the duration of application. Failure analysis thus generates an important feedback loop for the qualification process, identifying the root cause of the failure.

The information on the conditions of the application allow defects to be solved and is therefore indispensable for the anamneses of the system, contributing to a Zero Defect Strategy in the supply chain.

Join us in Brugg to find out more!

Register online at [www.roodmicrotec.com](http://www.roodmicrotec.com)



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